

Lec 14 MOSFETs

$$V_G = \phi_s + \gamma \sqrt{\phi_s} = 2\phi_f + \gamma \sqrt{2\phi_f}$$

Gate voltage.

Surface potential

$$\frac{\Delta E_2}{q} = \frac{\Delta E_1}{q}$$

Strong inversion

$$\Delta E_2 = \frac{kT}{q} \ln \frac{N_D}{n_i} = q\phi_f$$

$$\phi_s = \frac{1}{q} (\Delta E_2 + \Delta E_1) = \frac{2\phi_f}{q} \Delta E_2 = \frac{2kT}{q} \ln \frac{N_D}{n_i}$$

$$\Rightarrow V_{T0}' = \frac{2kT}{q} \ln \frac{N_D}{n_i} + \gamma \sqrt{\frac{2kT}{q} \ln \frac{N_D}{n_i}} \quad \phi_f = \frac{kT}{q} \ln \left(\frac{N_D}{n_i}\right)$$

Correction factors

① $\Phi_{ms} = q(\bar{\Phi}_m - \bar{\Phi}_s) \rightarrow$ Offset applied to get to flat band response.

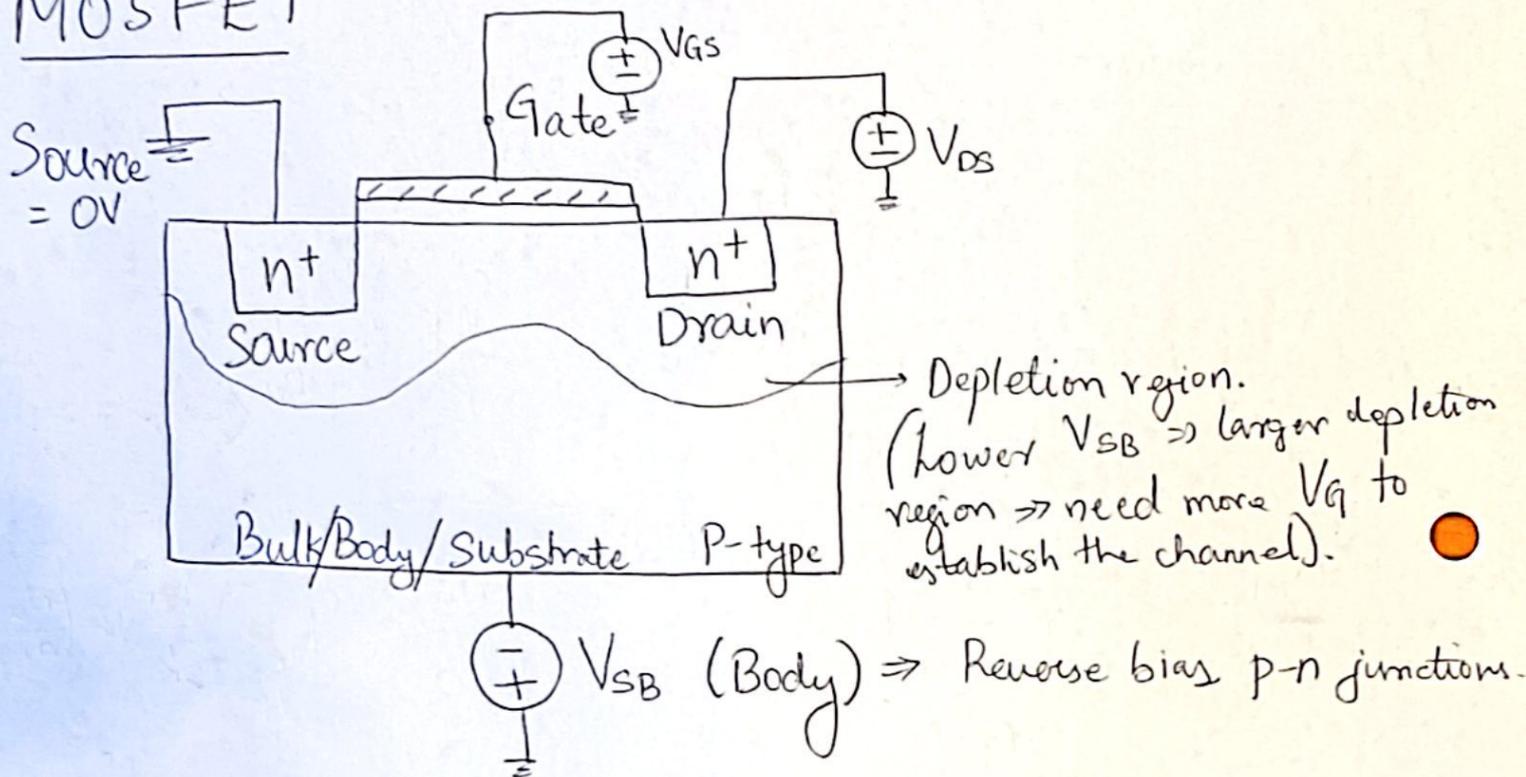
② $\frac{Q_{ss}}{C_{ox}}$ is an additional voltage due to charges trapped at Si-Ox interface.

$V_{FB} = \Phi_{ms} - \frac{Q_{ss}}{C_{ox}} - \frac{Q_T}{C_{ox}}$ is the "flat band voltage" which needs to applied to get to a flat band.
 \rightarrow implantation charge.

$$\Rightarrow V_{T0} = V_{FB} + 2\phi_f + \gamma \sqrt{2\phi_f} \quad \text{Threshold voltage}$$

Voltage applied to reach strong inversion

MOSFET



- > The n^+ wells ^(charge supply since highly doped) now acts as a large source & sink of minority carriers to enable faster "strong inversion".
- > Note a fourth "body terminal". This voltage changes the size of the depletion region. Therefore both V_{GS} & V_{SB} control the surface charge distribution.

Recall,

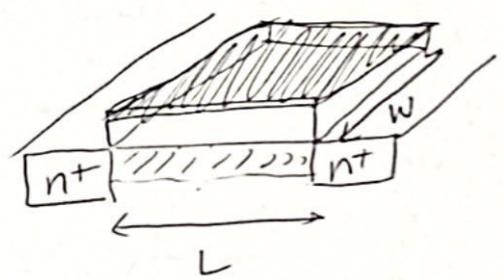
$$V_{T\phi} = \underbrace{V_{FB}}_{\text{constant to account for assumptions}} + \underbrace{2\phi_f}_{\text{Definition of Strong inversion}} + \gamma \sqrt{\underbrace{2\phi_f + V_{SB}}_{\text{oxide}}}$$

Body Effect.

V_{SB} is applied across the oxide \Rightarrow square root dependence.

Current - Voltage Relationship (Assume V_{DS} is small).

> Total charge in channel



$$Q_{ch} = W \cdot L \cdot Q_{inv}$$

\rightarrow total charge per unit height

$$Q_{ch} = C \cdot (V_{GS} - V_{th}) \rightarrow \text{(ignoring charges stored during weak inversion.)}$$

$$= C_{ox} \cdot W \cdot L \cdot (V_{GS} - V_{th})$$

> Avg. time for electron to go from source to drain

$$\tau_F = \frac{L}{v_d} = \frac{L}{\mu_n E} = \frac{L}{\mu_n \cdot \frac{V_{DS}}{L}} = \frac{L^2}{\mu_n V_{DS}}$$

\uparrow drift velocity \downarrow mobility of e^-

$$\Rightarrow I_D = \frac{q_{ch}}{C_F} = \frac{WL C_{ox} (V_{GS} - V_T)}{\frac{L^2}{\mu_n V_{DS}}}$$

Equivalent to Saturation
in BJT

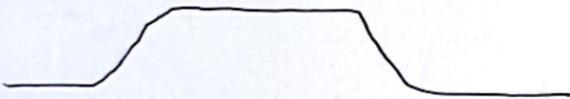
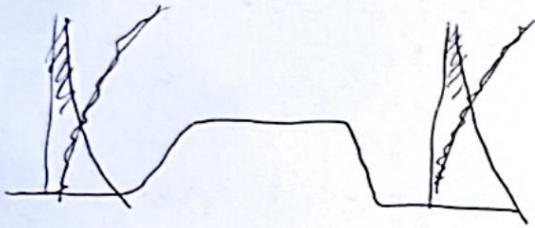
Triode
(aka linear)

V_{GS} large V_{DS} small

Energy Band Picture

$$I_D = \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_T) V_{DS}$$

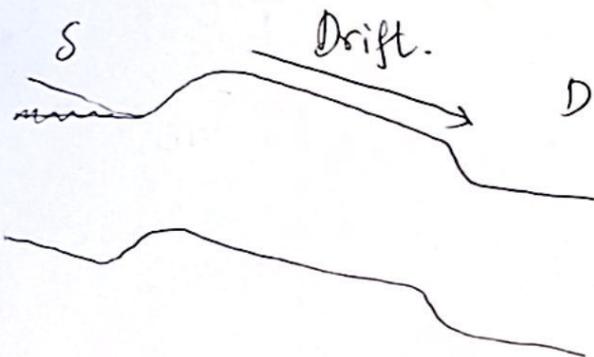
for small V_{DS} .
→ 'Trans Resistor'
(Not a real resistor ⇒ not due to constant conductivity)



Apply V_{GS}
→
Formation of Channel.



Now Apply V_{DS}



→ I_D is therefore a drift current.